



EXPRESS MAIL NO. EV207700042US
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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10 /B

Applicant : Wade J. Doll
Application No. : 09/705,367
Filed : November 3, 2000
For : SEMICONDUCTOR CIRCULAR AND RADIAL FLOW COOLER

Examiner : Leonard R. Leo
Art Unit : 3743
Docket No. : 901115.434
Date : November 13, 2002

Box RCE
Commissioner for Patents
Washington, DC 20231

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AMENDMENT

TECHNOLOGY CENTER R3700

Commissioner for Patents:

In response to the Office Action dated August 27, 2002, please amend the application as follows:

In the Specification:

Please replace the paragraph beginning at page 5, line 4, with the following rewritten paragraph:

As best seen in Figures 1 and 2A, the heat exchanger assembly 10 is typically mounted atop a semiconductor package 12. The semiconductor package typically comprises a semiconductor chip 17, socket 14, and a substrate 16 within which the semiconductor chip is disposed, and a lid or heat spreader 18.

Please replace the paragraph beginning at page 8, line 19, with the following rewritten paragraph:

As indicated previously, the heat exchanger 24, which includes the cylindrical turret head 20 and the fin plate 22, can be rotated within the heat exchanger assembly 10. This